



QUAD production

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Nikhef/Bonn LepCol meeting
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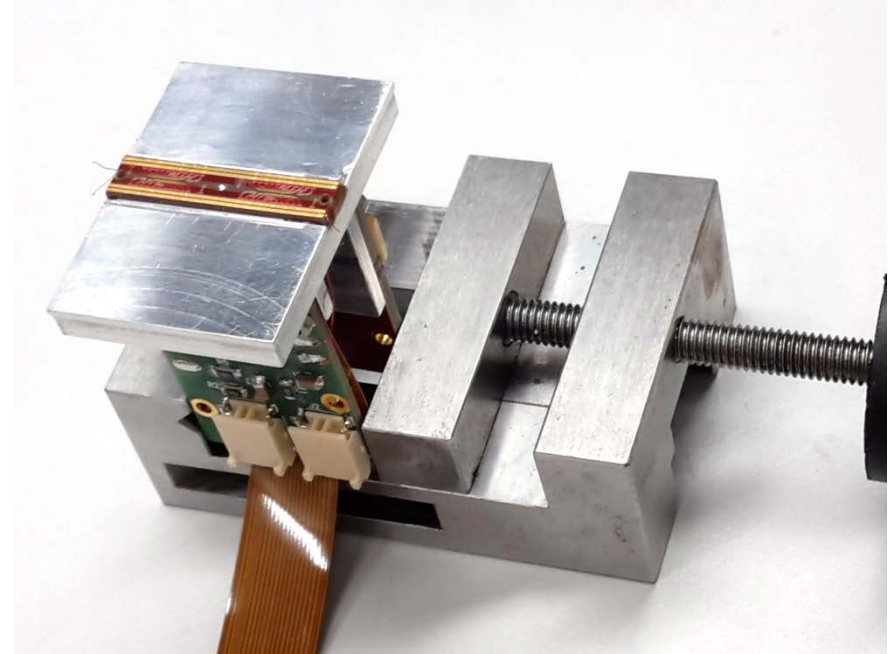
Simplified overview production

QUAD	started	Mech. assy	Wire bonded	DAQ/HV test	Ready	Remarks
10	X	X	X			DEMO, not electrically working
11	X	X	X	X	X	~30 um alignment error
12	X	X	X			~30 um alignment error
13	X	X	X			
14	X	X				
15	X	X				
16	X	X				
17	X					
18	X					
19	X					
20						
21						
22						
23						
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Production issues

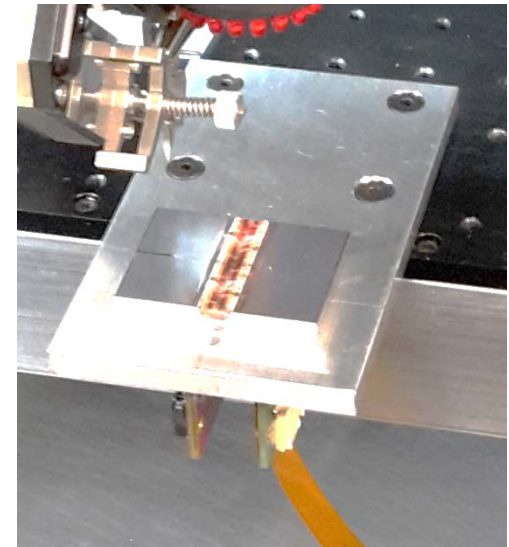
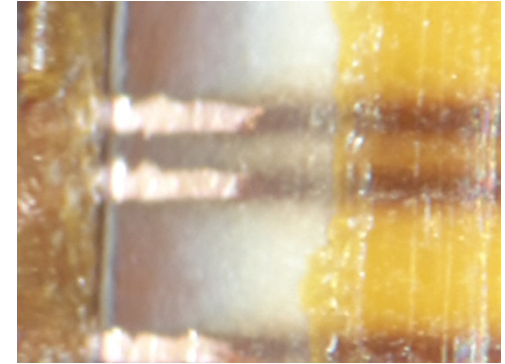
- Components available for full production (14 QUADs)
 - Wirebond boards + flexes
 - HV boards
 - COCAs + stumps
 - Consumables
 - Glues + needles
 - HV wire
 - Thermal tape (out of production)
 - Screws

- Bottle necks
 - Presently only chips until QUAD 17
 - Guard electrodes not before mid November



Production issues cntd

- Chip W23-I5 has small grid indentation
 - Might give HV short => chip discarded
- Machining wirebond board
 - Flex on chip 14 damaged but possibly still usable
- DAQ testing
 - QUAD 13 did not work
 - E-prom on LV board has to be programmed
 - We have to do this for all new QUADs
 - But no chips are needed for this
 - 2nd SPIDR board now available
- Wirebonding
 - Attachment problems on chips
 - => ~5 wirebonds/QUAD have to be redone



New testbox

- Optical glass plates delivered
- Mechanics almost finished
- **But again delay with the production of the glass fibre components**
 - **Mid November**

- DAQ
 - 2 SPIDR boards available
 - Including the one we use for production testing
 - Concentrator boards available
 - Power boards ordered

 - **But programming concentrator not yet done**

